Time-Lag SMD Fuses

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RoHS Compliant

Description

The SMD fuses stand out due to their ultra-small size and excellent electrical performance, reliability and quality. The solderfree design provides outstanding on-off and temperature cycling characteristics during operation and also makes our SMD fuses more heat and shock tolerant than typical sub-miniature fuses.

Applications

Industrial products such as cellphones, DVD players, battery packs, hard disk drives and digital cameras

Features

- Rapid interruption of excessive current
- Compatible with reflow and wave soldering
- Ceramic and glass construction
- Excellent environmental integrity
- Non-resettable fuse design
- · Lead-free and Halogen-free
- Designed to UL 248-14

Specifications

Operating Temperature: -55°C to +125°CStorage Conditions: +10°C to +60°CRelative Humidity: \leq 75% yearly average without dew, maximum 30 days at 95%Vibration Resistance: 24 cycles at 15 min. each
10-60Hz at 0.75mm amplitude

60-2000Hz at 10g acceleration

Electrical Characteristics

Part Number	Rated Current	Rated Voltage	Typical Voltage Drop (mV)	Breaking Capacity	Typical Cold Resistance (mΩ)	Typical Melting I²t (A²sec)
MP001606	1A	12V AC 63V DC	500	50A @ 12V AC 50A @ 63V AC	480	0.11
MP001607	2A		310		140	0.41
MP001608	3A		183		50	1.5
MP001609	4A		170		34	2.5
MP001610	5A	12V AC 32V DC	138	100A @ 12V AC 100A @ 32V DC	21.5	4

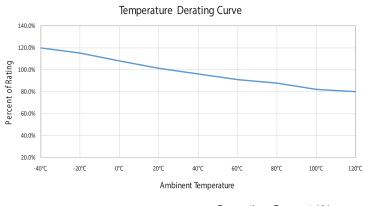
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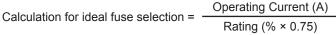


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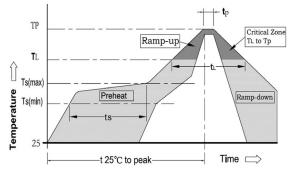
Average Time Current (I-T) Curves

Temperature Derating Curve





Soldering Parameters



	Profile Feature	Pb-Free Assembly	
Average Ramp-UP Rate(Tsmax to Tp)		3°C/s Max.	
	Temperature Min (Ts min)	150°C	
Preheat	Temperature Max (Ts max)	200°C	
	Time (Tsmin to Ts max)	60sec to 120sec	
Peak Tempe	erature (TP)	260°C	
Time within Temperature	5°C of actual Peak e(TP)	5sec	
Melting tin time (TL)		20sec to 40sec	
Ramp-Dowr	Rate	6°C/s Max.	
Time 25°C to Temperature		8 minutes Max.	

1. Infrared Reflow:

Temperature: 260°C Time: 5sec Max. Recommend reflow profile

2. Wave Soldering:

Reservoir Temperature: 260°C Time in Reservoir: 10sec Max.

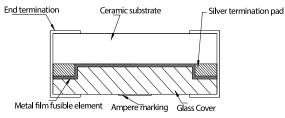
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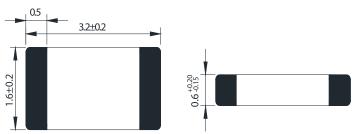
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Mechanical Specifications



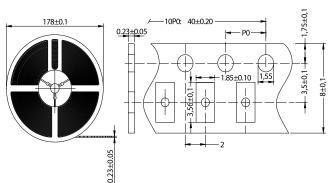
Diagram



Packing

Packing Information

Taping details



Dimensions : Millimetres

Part Number Table

Description	Part Number
SMD Fuse, Time-Lag, 1A, 12V AC, 63V DC, 1206	MP001606
SMD Fuse, Time-Lag, 2A, 12V AC, 63V DC, 1206	MP001607
SMD Fuse, Time-Lag, 3A, 12V AC, 63V DC, 1206	MP001608
SMD Fuse, Time-Lag, 4A, 12V AC, 63V DC, 1206	MP001609
SMD Fuse, Time-Lag, 5A, 12V AC, 32V DC, 1206	MP001610

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